

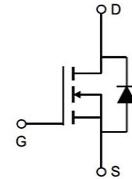
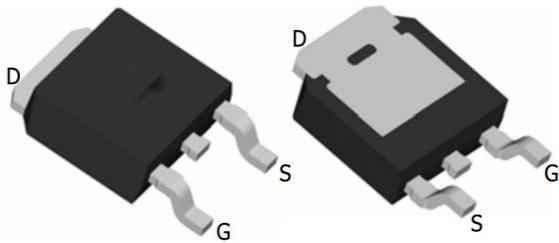
30V /25A Single N Power MOSFET
General Description

30V /25A Single N Power MOSFET

Very low on-resistance RDS(on) @ VGS=4.5 V

Pb-free lead plating; RoHS compliant

V_{DS}	30	V
R_{DS(on),TYP}@VGS=10V	23.1	mΩ
R_{DS(on),TYP}@VGS=4.5	36.3	mΩ
I_D	25	A



Part ID	Package Type	Marking	Tape and reel infomation
SM480T9RL	TO-252	25N03	2500


 100% UIS Tested
100% RG Tested

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	20	±V
Continuous Drain Current A	I _D	25.0	A
		18.0	
Pulsed Drain Current B	I _{DM}	40.0	
Avalanche Current G	I _{AR}	8.0	
Repetitive avalanche energy L=0.1mH G	E _{AR}	18.4	mJ
Power Dissipation A	P _D	21	W
		11	
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient A	R _{θJA}	82	123	°C/W
Maximum Junction-to-Ambient A		165	198	°C/W
Maximum Junction-to-Lead c	R _{θJL}	49	79	°C/W

STATIC PARAMETERS

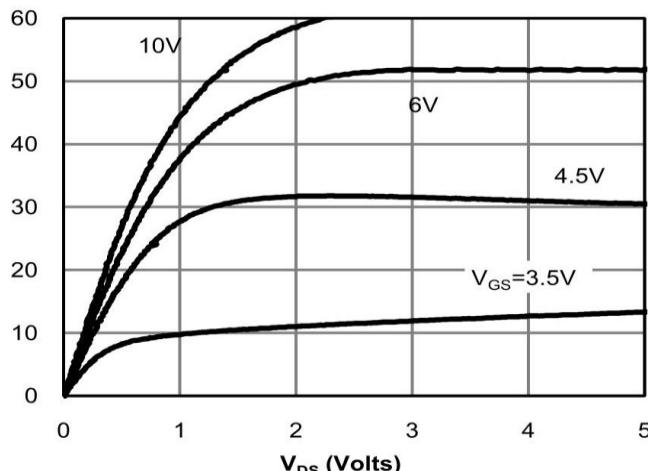
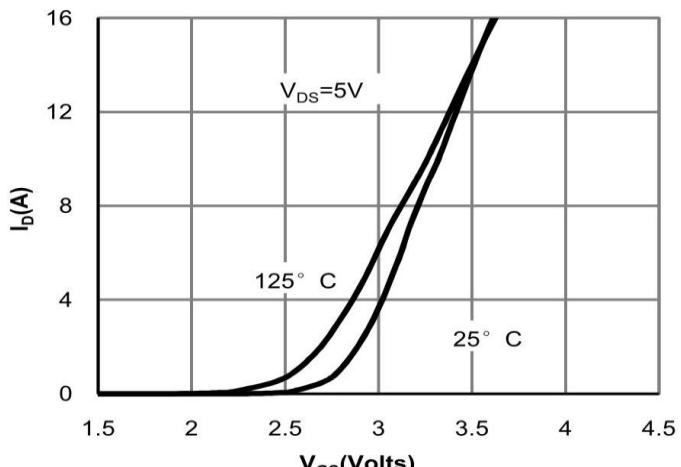
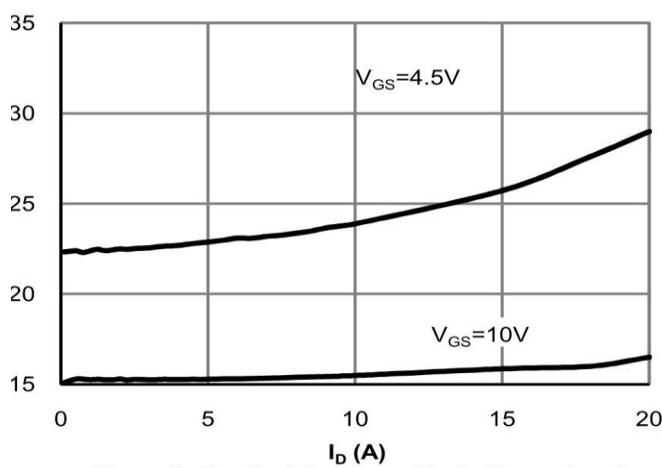
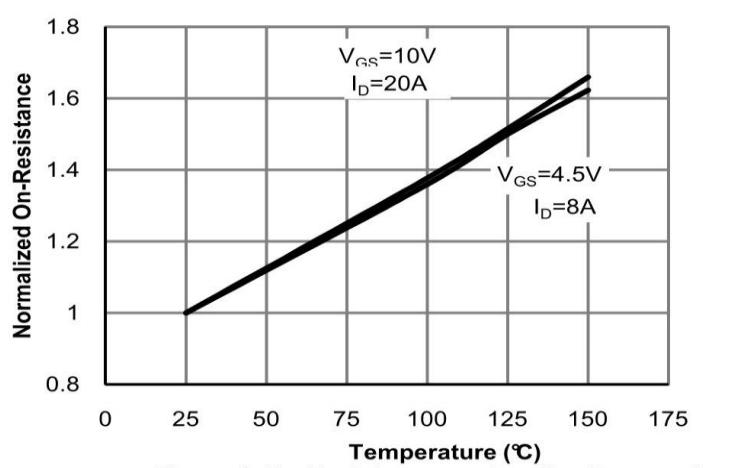
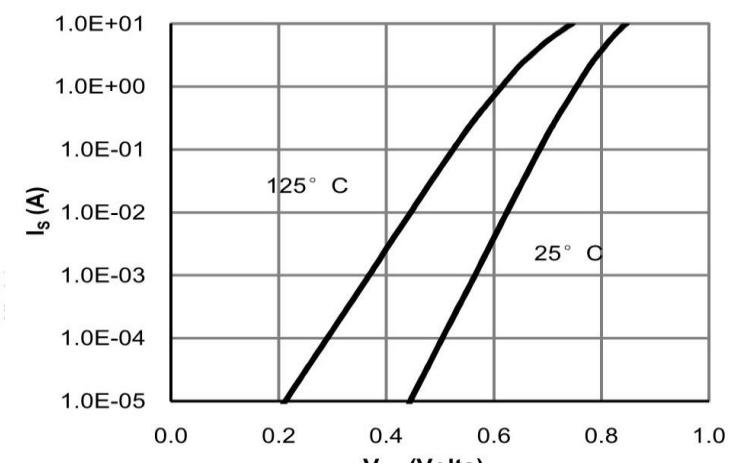
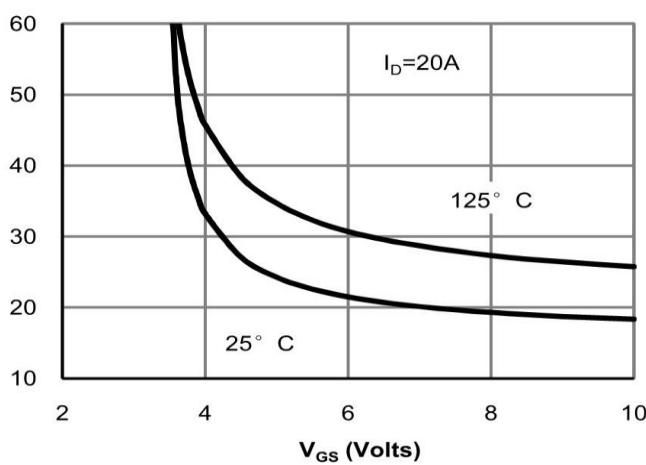
Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = -250\mu A, V_{GS} = 0V$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$			1	uA
					5	
I_{GSS}	Gate-Body leakage current	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	2	2.6	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=20A$		23.1	33.0	$m\Omega$
		$V_{GS}=4.5V, I_D=20A$		36.3	47.2	
g_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=20A$		47		S
V_{SD}	Diode Forward Voltage	$I_S=1A, V_{GS}=102V$		0.72	1	V
I_S	Maximum Body-Diode Continuous Current				25	A

DYNAMIC PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=15V, f=1MHz$		373	455	pF
C_{oss}	Output Capacitance			67	82	pF
C_{rss}	Reverse Transfer Capacitance			41	48	pF
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$			0.8	Ω

SWITCHING PARAMETERS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$Q_g(10V)$	Total Gate Charge	$V_{GS}=10V, V_{DS}=15V, I_D=20A$		3.5		nC
$Q_g 4.5V)$	Total Gate Charge			1.75		
Q_{gs}	Gate Source Charge			1.12		
Q_{gd}	Gate Drain Charge			1.6		
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10V, V_{DS}=15V, RL=0.75\Omega, RGEN=3\Omega$		5.25		ns
t_r	Turn-On Rise Time			4.2		
$t_{D(off)}$	Turn-Off DelayTime			14.7		
t_f	Turn-Off Fall Time			4.725		
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-8A, dI/dt=500A/\mu s$		10.5		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=18A, dI/dt=500A/\mu s$		4.5		nC

CAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature


CAL ELECTRICAL AND THERMAL CHARACTERISTICS

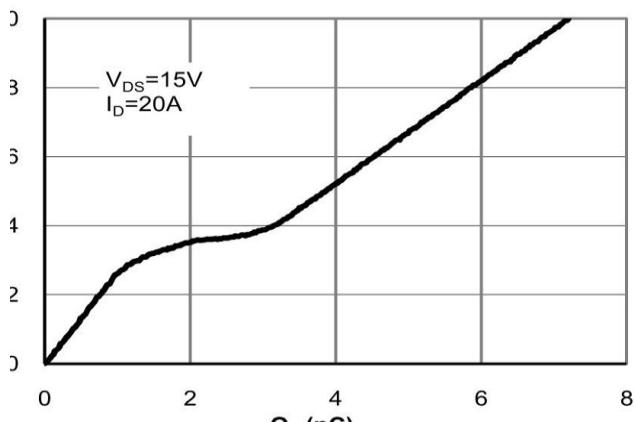


Figure 7: Gate-Charge Characteristics

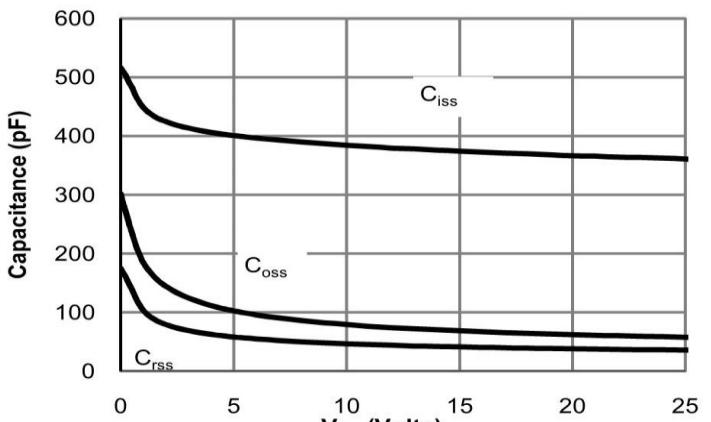


Figure 8: Capacitance Characteristics

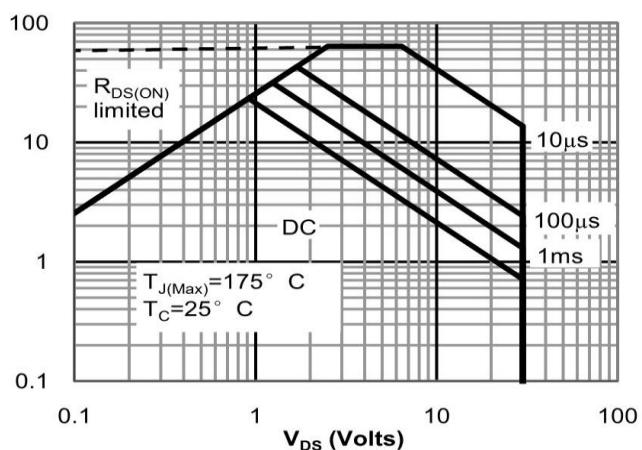


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

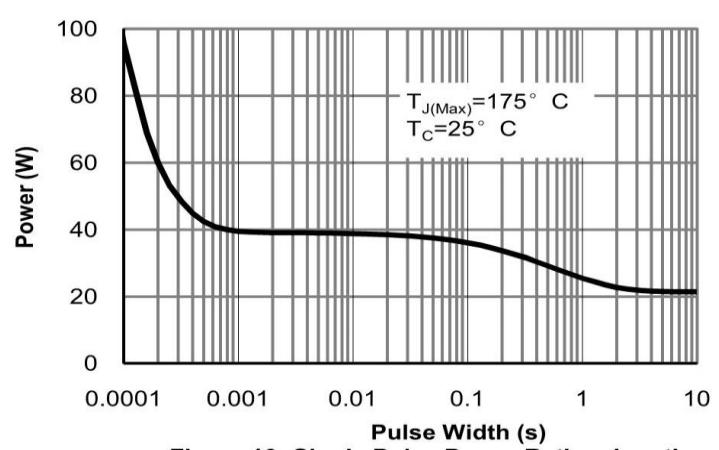


Figure 10: Single Pulse Power Rating Junction Case (Note F)

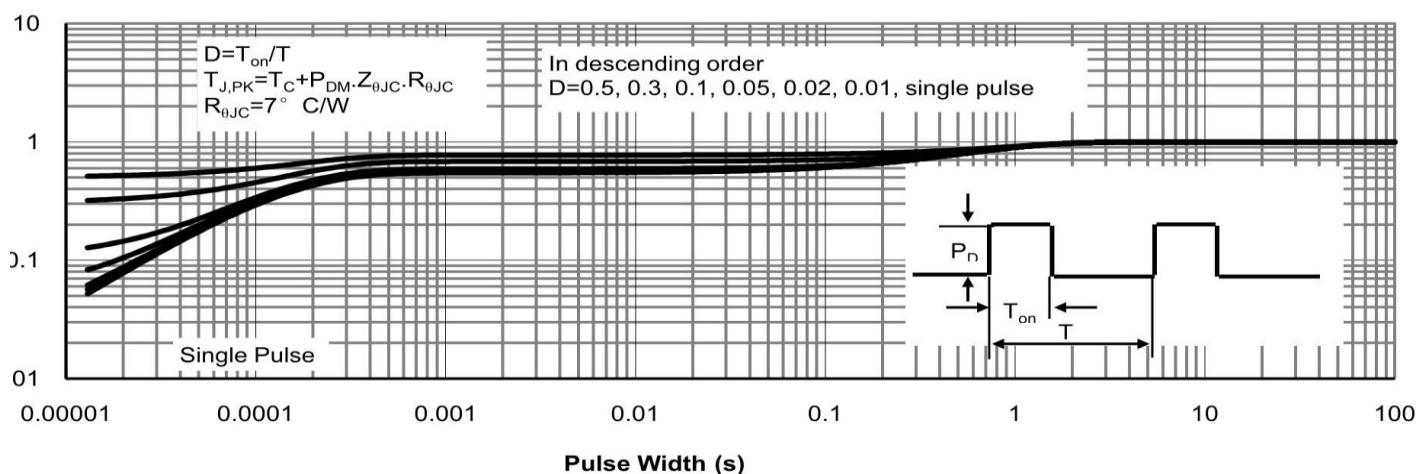


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)